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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	12
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-VQFN Exposed Pad
Supplier Device Package	16-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f676t-i-ml

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PIC16F630/676

TABLE 2-1: PIC16F630/676 SPECIAL REGISTERS SUMMARY BANK 0

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Page
Bank 0											
00h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	20, 63
01h	TMR0	Timer0 Module's Register								xxxx xxxx	31
02h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	19
03h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	\overline{TO}	\overline{PD}	Z	DC	C	0001 1xxx	13
04h	FSR	Indirect data memory Address Pointer								xxxx xxxx	20
05h	PORTA	—	—	I/O Control Registers						--xx xxxx	21
06h	—	Unimplemented								—	—
07h	PORTC	—	—	I/O Control Registers						--xx xxxx	28
08h	—	Unimplemented								—	—
09h	—	Unimplemented								—	—
0Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of program counter					---0 0000	19
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RAIE	TOIF	INTF	RAIF	0000 0000	15
0Ch	PIR1	EEIF	ADIF	—	—	CMIF	—	—	TMR1IF	00-- 0--0	17
0Dh	—	Unimplemented								—	—
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1								xxxx xxxx	34
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1								xxxx xxxx	34
10h	T1CON	—	T1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	-000 0000	36
11h	—	Unimplemented								—	—
12h	—	Unimplemented								—	—
13h	—	Unimplemented								—	—
14h	—	Unimplemented								—	—
15h	—	Unimplemented								—	—
16h	—	Unimplemented								—	—
17h	—	Unimplemented								—	—
18h	—	Unimplemented								—	—
19h	CMCON	—	COUT	—	CINV	CIS	CM2	CM1	CM0	-0-0 0000	39
1Ah	—	Unimplemented								—	—
1Bh	—	Unimplemented								—	—
1Ch	—	Unimplemented								—	—
1Dh	—	Unimplemented								—	—
1Eh	ADRESH ⁽³⁾	Most Significant 8 bits of the left shifted A/D result or 2 bits of right shifted result								xxxx xxxx	46
1Fh	ADCON0 ⁽³⁾	ADFM	VCFG	—	CHS2	CHS1	CHS0	$\overline{GO/DONE}$	ADON	00-0 0000	47, 63

Legend: — = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition shaded = unimplemented

Note 1: Other (non Power-up) Resets include MCLR Reset, Brown-out Detect and Watchdog Timer Reset during normal operation.

2: IRP and RP1 bits are reserved, always maintain these bits clear.

3: PIC16F676 only.

PIC16F630/676

2.4 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses data pointed to by the File Select Register (FSR). Reading INDF itself indirectly will produce 00h. Writing to the INDF register indirectly results in a no operation (although Status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 2-4.

A simple program to clear RAM location 20h-2Fh using indirect addressing is shown in Example 2-1.

EXAMPLE 2-1: INDIRECT ADDRESSING

```
MOVLW 0x20 ;initialize pointer
MOVWF FSR ;to RAM
NEXT   CLRF INDF ;clear INDF register
      INCF FSR ;inc pointer
      BTFSS FSR,4 ;all done?
      GOTO NEXT ;no clear next
CONTINUE ;yes continue
```

FIGURE 2-4: DIRECT/INDIRECT ADDRESSING PIC16F630/676

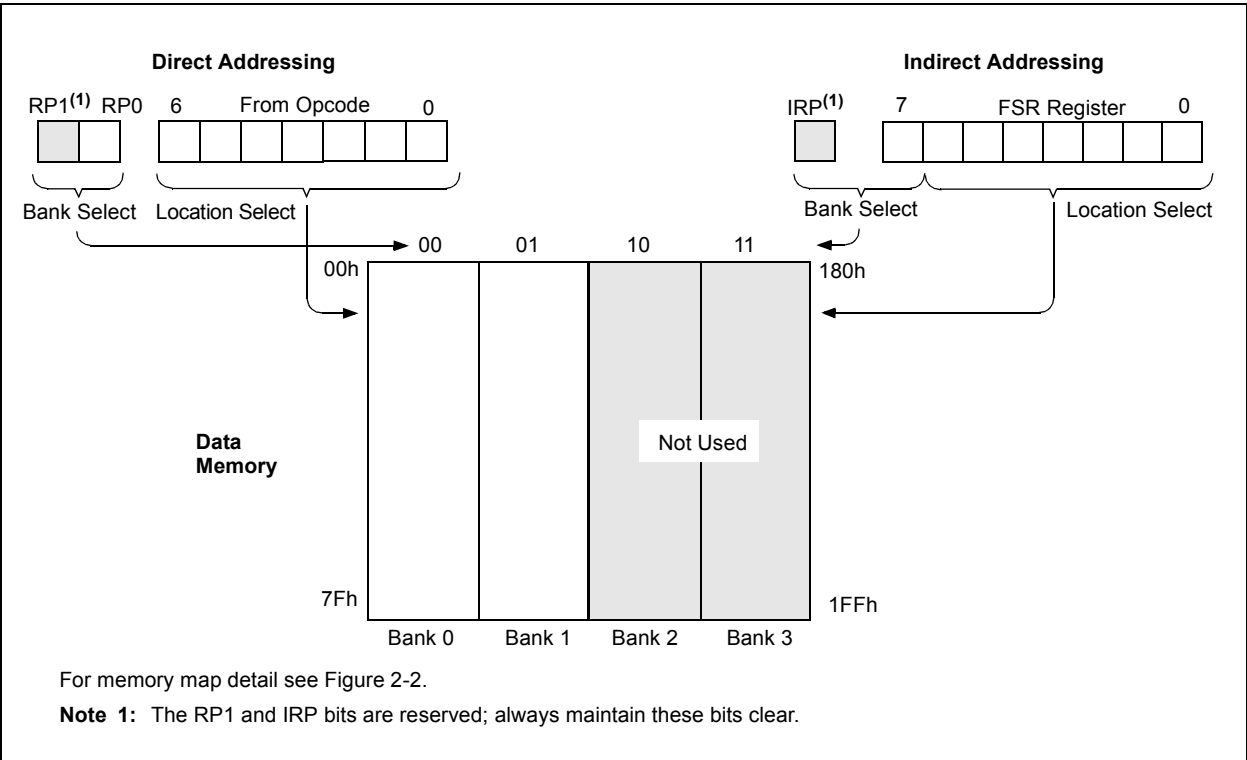


TABLE 3-1: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
05h	PORTA	—	—	RA5	RA4	RA3	RA2	RA1	RA0	--xx xxxx	--uu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 000u
19h	CMCON	—	COUT	—	CINV	CIS	CM2	CM1	CM0	-0-0 0000	-0-0 0000
81h	OPTION_REG	RAPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	--11 1111	--11 1111
91h	ANSEL ⁽¹⁾	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111
95h	WPUA	—	—	WPUA5	WPUA4	—	WPUA2	WPUA1	WPUA0	--11 -111	--11 -111
96h	IOCA	—	—	IOCA5	IOCA4	IOCA3	IOCA2	IOCA1	IOCA0	--00 0000	--00 0000

Note 1: PIC16F676 only.

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

REGISTER 3-5: PORTC — PORTC REGISTER (ADDRESS: 07h)

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	
—	—	RC5	RC4	RC3	RC2	RC1	RC0	
bit 7								bit 0

bit 7-6: **Unimplemented:** Read as '0'

bit 5-0: **PORTC<5:0>:** General Purpose I/O pin bits

1 = Port pin is >V_{IH}

0 = Port pin is <V_{IL}

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

- n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

REGISTER 3-6: TRISC — PORTC TRI-STATE REGISTER (ADDRESS: 87h)

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	
bit 7								bit 0

bit 7-6: **Unimplemented:** Read as '0'

bit 5-0: **TRISC<5:0>:** PORTC Tri-State Control bits

1 = PORTC pin configured as an input (tri-stated)

0 = PORTC pin configured as an output

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

- n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

TABLE 3-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
07h	PORTC	—	—	RC5	RC4	RC3	RC2	RC1	RC0	--xx xxxx	--uu uuuu
87h	TRISC	—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	--11 1111	--11 1111
91h	ANSEL ⁽¹⁾	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111

Note 1: PIC16F676 only.

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTC.

5.1 Timer1 Modes of Operation

Timer1 can operate in one of three modes:

- 16-bit timer with prescaler
- 16-bit synchronous counter
- 16-bit asynchronous counter

In Timer mode, Timer1 is incremented on every instruction cycle. In Counter mode, Timer1 is incremented on the rising edge of the external clock input T1CKI. In addition, the Counter mode clock can be synchronized to the microcontroller system clock or run asynchronously.

In counter and timer modules, the counter/timer clock can be gated by the T1G input.

If an external clock oscillator is needed (and the microcontroller is using the INTOSC w/o CLKOUT), Timer1 can use the LP oscillator as a clock source.

Note: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge.

5.2 Timer1 Interrupt

The Timer1 register pair (TMR1H:TMR1L) increments to FFFFh and rolls over to 0000h. When Timer1 rolls over, the Timer1 interrupt flag bit (PIR1<0>) is set. To enable the interrupt on rollover, you must set these bits:

- Timer1 interrupt Enable bit (PIE1<0>)
- PEIE bit (INTCON<6>)
- GIE bit (INTCON<7>).

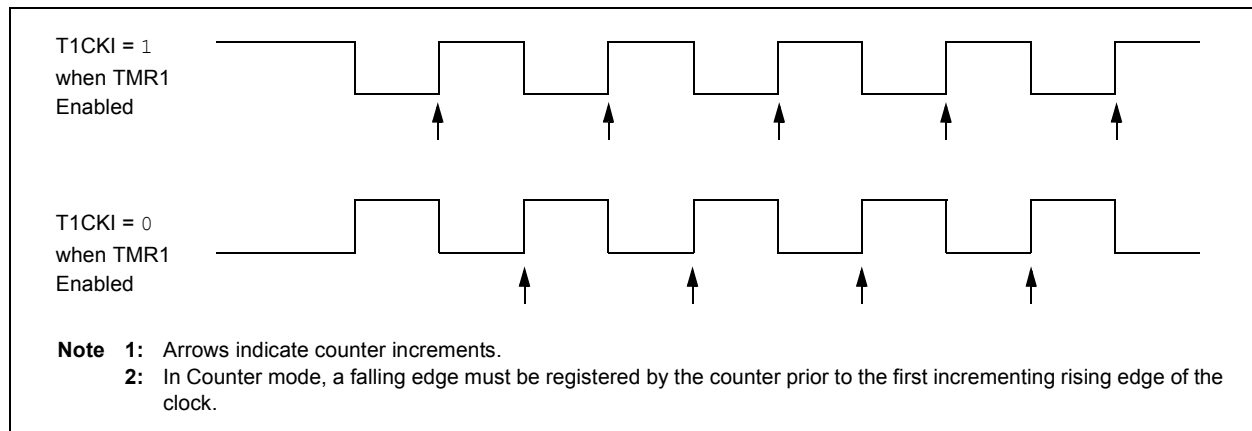
The interrupt is cleared by clearing the TMR1IF in the Interrupt Service Routine.

Note: The TMR1H:TMR1L register pair and the TMR1IF bit should be cleared before enabling interrupts.

5.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4, or 8 divisions of the clock input. The T1CKPS bits (T1CON<5:4>) control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

FIGURE 5-2: TIMER1 INCREMENTING EDGE

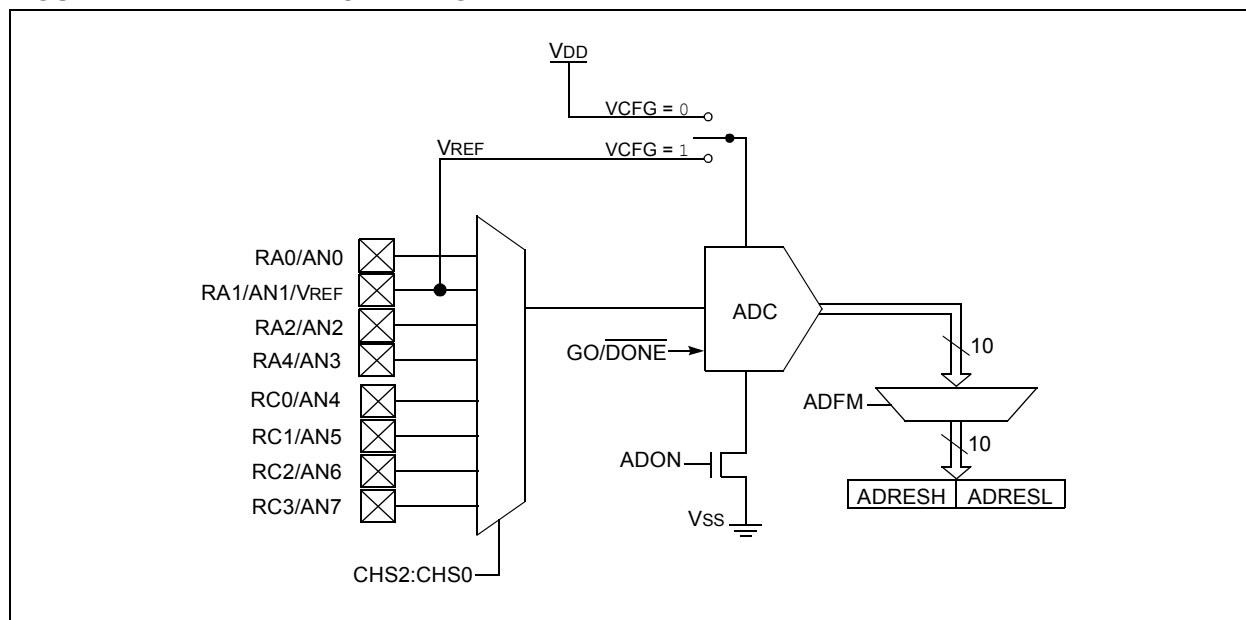


7.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE (PIC16F676 ONLY)

The Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 10-bit binary representation of that signal. The PIC16F676 has eight analog inputs, multiplexed into one sample and hold

circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a binary result via successive approximation and stores the result in a 10-bit register. The voltage reference used in the conversion is software selectable to either VDD or a voltage applied by the VREF pin. Figure 7-1 shows the block diagram of the A/D on the PIC16F676.

FIGURE 7-1: A/D BLOCK DIAGRAM



7.1 A/D Configuration and Operation

There are three registers available to control the functionality of the A/D module:

1. ADCON0 (Register 7-1)
2. ADCON1 (Register 7-2)
3. ANSEL (Register 7-3)

7.1.1 ANALOG PORT PINS

The ANS7:ANS0 bits (ANSEL<7:0>) and the TRISA bits control the operation of the A/D port pins. Set the corresponding TRISA bits to set the pin output driver to its high-impedance state. Likewise, set the corresponding ANS bit to disable the digital input buffer.

Note: Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

7.1.2 CHANNEL SELECTION

There are eight analog channels on the PIC16F676, AN0 through AN7. The CHS2:CHS0 bits (ADCON0<4:2>) control which channel is connected to the sample and hold circuit.

7.1.3 VOLTAGE REFERENCE

There are two options for the voltage reference to the A/D converter: either VDD is used, or an analog voltage applied to VREF is used. The VCFG bit (ADCON0<6>) controls the voltage reference selection. If VCFG is set, then the voltage on the VREF pin is the reference; otherwise, VDD is the reference.

7.1.4 CONVERSION CLOCK

The A/D conversion cycle requires 11 TAD. The source of the conversion clock is software selectable via the ADCS bits (ADCON1<6:4>). There are seven possible clock options:

- Fosc/2
- Fosc/4
- Fosc/8
- Fosc/16
- Fosc/32
- Fosc/64
- FRC (dedicated internal oscillator)

For correct conversion, the A/D conversion clock (1/TAD) must be selected to ensure a minimum TAD of 1.6 μ s. Table 7-1 shows a few TAD calculations for selected frequencies.

REGISTER 7-1: ADCON0 — A/D CONTROL REGISTER (ADDRESS: 1Fh)

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	VCFG	—	CHS2	CHS1	CHS0	GO/DONE	ADON

bit 7

bit 0

bit 7 **ADFM:** A/D Result Formed Select bit

1 = Right justified

0 = Left justified

bit 6 **VCFG:** Voltage Reference bit

1 = VREF pin

0 = VDD

bit 5 **Unimplemented:** Read as zero

bit 4-2 **CHS2:CHS0:** Analog Channel Select bits

000 = Channel 00 (AN0)

001 = Channel 01 (AN1)

010 = Channel 02 (AN2)

011 = Channel 03 (AN3)

100 = Channel 04 (AN4)

101 = Channel 05 (AN5)

110 = Channel 06 (AN6)

111 = Channel 07 (AN7)

bit 1 **GO/DONE:** A/D Conversion Status bit

1 = A/D conversion cycle in progress. Setting this bit starts an A/D conversion cycle.

This bit is automatically cleared by hardware when the A/D conversion has completed.

0 = A/D conversion completed/not in progress

bit 0 **ADON:** A/D Conversion Status bit

1 = A/D converter module is operating

0 = A/D converter is shut-off and consumes no operating current

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

- n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

REGISTER 7-2: ADCON1 — A/D CONTROL REGISTER 1 (ADDRESS: 9Fh)

U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	ADCS2	ADCS1	ADCS0	—	—	—	—

bit 7

bit 0

bit 7: **Unimplemented:** Read as '0'

bit 6-4: **ADCS<2:0>:** A/D Conversion Clock Select bits

000 = Fosc/2

001 = Fosc/8

010 = Fosc/32

x11 = FRC (clock derived from a dedicated internal oscillator = 500 kHz max)

100 = Fosc/4

101 = Fosc/16

110 = Fosc/64

bit 3-0: **Unimplemented:** Read as '0'

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

- n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

7.2 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-3. The source impedance (R_s) and the internal sampling switch (R_{SS}) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (R_{SS}) impedance varies over the device voltage (V_{DD}), see Figure 7-3. **The maximum recommended impedance for analog sources is 10 k Ω .** As the impedance

is decreased, the acquisition time may be decreased. After the analog input channel is selected (changed), this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

To calculate the minimum acquisition time, T_{ACQ} , see the PIC® Mid-Range Reference Manual (DS33023).

EQUATION 7-1: ACQUISITION TIME

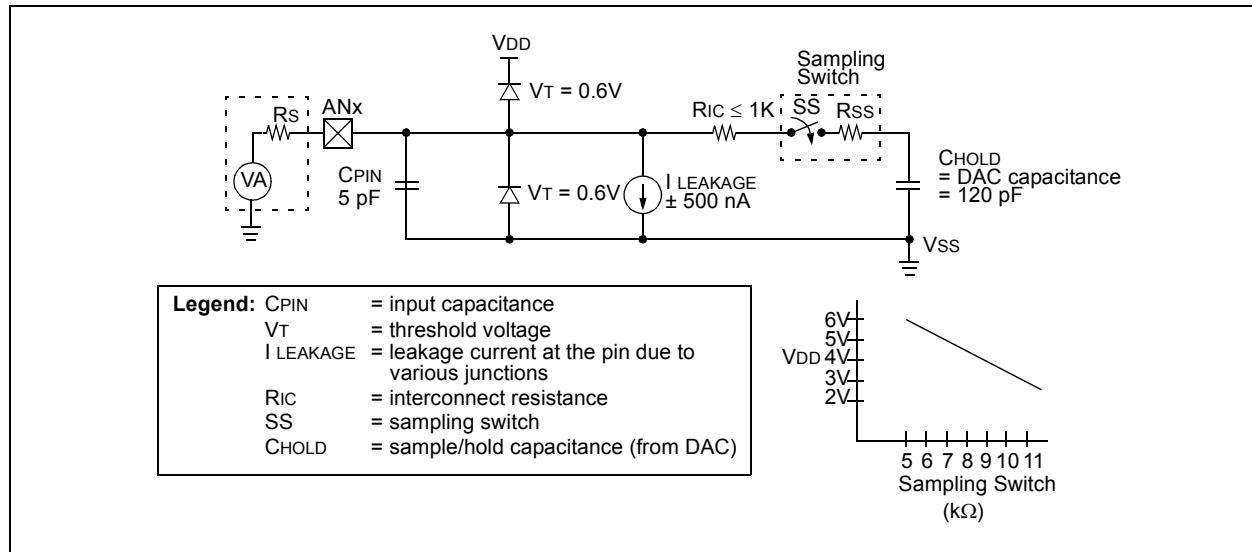
$$\begin{aligned}
 T_{ACQ} &= \text{Amplifier Settling Time} + \\
 &\quad \text{Hold Capacitor Charging Time} + \\
 &\quad \text{Temperature Coefficient} \\
 &= T_{AMP} + T_C + T_{COFF} \\
 &= 2\mu s + T_C + [(\text{Temperature} - 25^\circ\text{C})(0.05\mu s/^\circ\text{C})] \\
 T_C &= \text{CHOLD} (R_{IC} + R_{SS} + R_s) \ln(1/2047) \\
 &= -120\text{pF} (1\text{k}\Omega + 7\text{k}\Omega + 10\text{k}\Omega) \ln(0.0004885) \\
 &= 16.47\mu s \\
 T_{ACQ} &= 2\mu s + 16.47\mu s + [(50^\circ\text{C} - 25^\circ\text{C})(0.05\mu s/^\circ\text{C})] \\
 &= 19.72\mu s
 \end{aligned}$$

Note 1: The reference voltage (V_{REF}) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 k Ω . This is required to meet the pin leakage specification.

FIGURE 7-3: ANALOG INPUT MODEL



9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

The PIC16F630/676 can be operated in eight different Oscillator Option modes. The user can program three Configuration bits (FOSC2 through FOSC0) to select one of these eight modes:

- LP Low-Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC External Resistor/Capacitor (2 modes)
- INTOSC Internal Oscillator (2 modes)
- EC External Clock In

Note: Additional information on oscillator configurations is available in the PIC® Mid-Range Reference Manual, (DS33023).

9.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (see Figure 9-1). The PIC16F630/676 oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may yield a frequency outside of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (see Figure 9-2).

FIGURE 9-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)

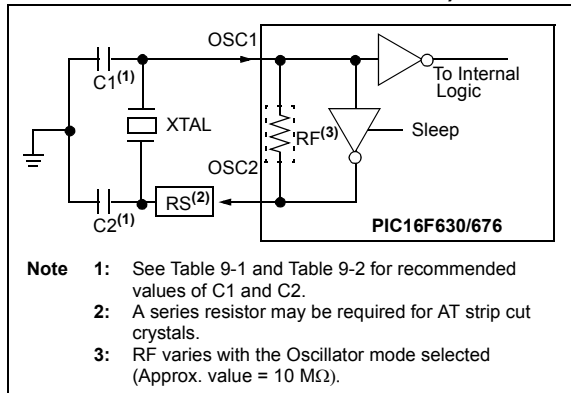


FIGURE 9-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT, EC, OR LP OSC CONFIGURATION)

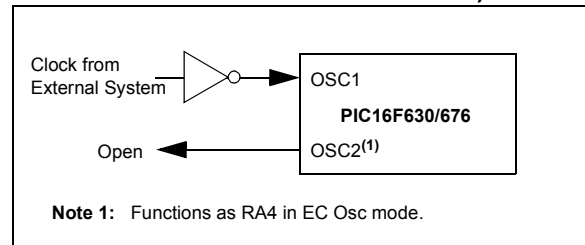


TABLE 9-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Characterized:			
Mode	Freq	OSC1(C1)	OSC2(C2)
XT	455 kHz	68-100 pF	68-100 pF
	2.0 MHz	15-68 pF	15-68 pF
	4.0 MHz	15-68 pF	15-68 pF
HS	8.0 MHz	10-68 pF	10-68 pF
	16.0 MHz	10-22 pF	10-22 pF

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Mode	Freq	OSC1(C1)	OSC2(C2)
LP	32 kHz	68-100 pF	68-100 pF
XT	100 kHz	68-150 pF	150-200 pF
	2 MHz	15-30 pF	15-30 pF
	4 MHz	15-30 pF	15-30 pF
HS	8 MHz	15-30 pF	15-30 pF
	10 MHz	15-30 pF	15-30 pF
	20 MHz	15-30 pF	15-30 pF

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

PIC16F630/676

9.2.3 EXTERNAL CLOCK IN

For applications where a clock is already available elsewhere, users may directly drive the PIC16F630/676 provided that this external clock source meets the AC/DC timing requirements listed in **Section 12.0 “Electrical Specifications”**. Figure 9-2 shows how an external clock circuit should be configured.

9.2.4 RC OSCILLATOR

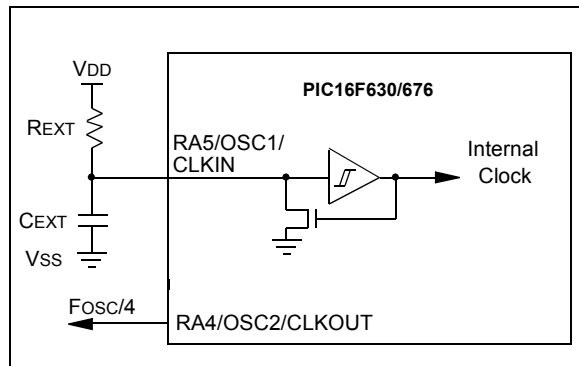
For applications where precise timing is not a requirement, the RC oscillator option is available. The operation and functionality of the RC oscillator is dependent upon a number of variables. The RC oscillator frequency is a function of:

- Supply voltage
- Resistor (REXT) and capacitor (CEXT) values
- Operating temperature

The oscillator frequency will vary from unit to unit due to normal process parameter variation. The difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to account for the tolerance of the external R and C components. Figure 9-3 shows how the R/C combination is connected.

Two options are available for this Oscillator mode which allow RA4 to be used as a general purpose I/O or to output Fosc/4.

FIGURE 9-3: RC OSCILLATOR MODE



9.2.5 INTERNAL 4 MHz OSCILLATOR

When calibrated, the internal oscillator provides a fixed 4 MHz (nominal) system clock. See Electrical Specifications, **Section 12.0 “Electrical Specifications”**, for information on variation over voltage and temperature.

Two options are available for this Oscillator mode which allow RA4 to be used as a general purpose I/O or to output Fosc/4.

9.2.5.1 Calibrating the Internal Oscillator

A calibration instruction is programmed into the last location of program memory. This instruction is a RETLW XX, where the literal is the calibration value. The literal is placed in the OSCCAL register to set the calibration of the internal oscillator. Example 9-1 demonstrates how to calibrate the internal oscillator. For best operation, decouple (with capacitance) VDD and VSS as close to the device as possible.

Note: Erasing the device will also erase the pre-programmed internal calibration value for the internal oscillator. The calibration value must be saved prior to erasing part as specified in the PIC16F630/676 Programming specification. Microchip Development Tools maintain all calibration bits to factory settings.

EXAMPLE 9-1: CALIBRATING THE INTERNAL OSCILLATOR

```
BSF    STATUS, RP0    ;Bank 1
CALL   3FFh           ;Get the cal value
MOVWF  OSCCAL          ;Calibrate
BCF    STATUS, RP0    ;Bank 0
```

9.2.6 CLKOUT

The PIC16F630/676 devices can be configured to provide a clock out signal in the INTOSC and RC Oscillator modes. When configured, the oscillator frequency divided by four (Fosc/4) is output on the RA4/OSC2/CLKOUT pin. Fosc/4 can be used for test purposes or to synchronize other logic.

9.7 Power-Down Mode (Sleep)

The Power-down mode is entered by executing a `SLEEP` instruction.

If the Watchdog Timer is enabled:

- WDT will be cleared but keeps running
- \overline{PD} bit in the STATUS register is cleared
- \overline{TO} bit is set
- Oscillator driver is turned off
- I/O ports maintain the status they had before `SLEEP` was executed (driving high, low, or high-impedance).

For lowest current consumption in this mode, all I/O pins should be either at V_{DD} , or V_{SS} , with no external circuitry drawing current from the I/O pin and the comparators and $CVREF$ should be disabled. I/O pins that are high-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The $T0CKI$ input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTA should be considered.

The \overline{MCLR} pin must be at a logic high level (V_{IHMC}).

Note: It should be noted that a Reset generated by a WDT time-out does not drive \overline{MCLR} pin low.

The first event will cause a device Reset. The two latter events are considered a continuation of program execution. The \overline{TO} and \overline{PD} bits in the STATUS register can be used to determine the cause of device Reset. The \overline{PD} bit, which is set on power-up, is cleared when Sleep is invoked. \overline{TO} bit is cleared if WDT Wake-up occurred.

When the `SLEEP` instruction is being executed, the next instruction ($PC + 1$) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the GIE bit is set (enabled), the device executes the instruction after the `SLEEP` instruction, then branches to the interrupt address (0004h). In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have an `NOP` after the `SLEEP` instruction.

Note: If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from Sleep. The `SLEEP` instruction is completely executed.

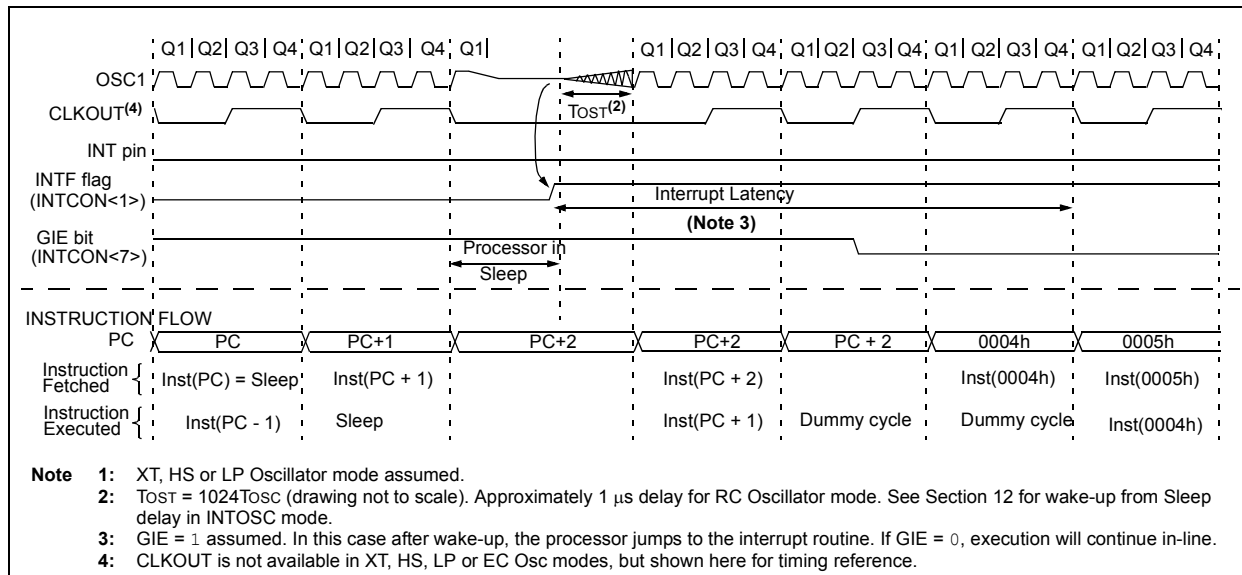
The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

9.7.1 WAKE-UP FROM SLEEP

The device can wake-up from Sleep through one of the following events:

1. External Reset input on \overline{MCLR} pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RA2/INT pin, PORTA change, or a peripheral interrupt.

FIGURE 9-13: WAKE-UP FROM SLEEP THROUGH INTERRUPT



9.8 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note: The entire data EEPROM and Flash program memory will be erased when the code protection is turned off. The INTOSC calibration data is also erased. See PIC16F630/676 Programming Specification for more information.

9.9 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution but are readable and writable during Program/Verify. Only the Least Significant 7 bits of the ID locations are used.

9.10 In-Circuit Serial Programming

The PIC16F630/676 microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for:

- power
- ground
- programming voltage

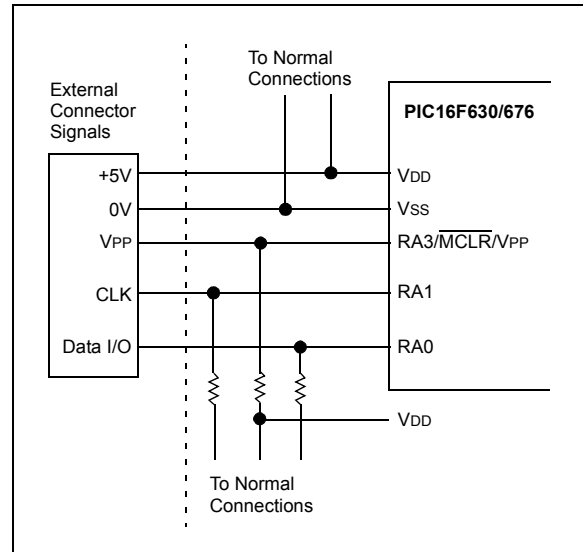
This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a Program/Verify mode by holding the RA0 and RA1 pins low, while raising the MCLR (VPP) pin from VIL to VIH (see Programming Specification). RA0 becomes the programming data and RA1 becomes the programming clock. Both RA0 and RA1 are Schmitt Trigger inputs in this mode.

After Reset, to place the device into Programming/Verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14 bits of program data are then supplied to or from the device, depending on whether the command was a load or a read. For complete details of serial programming, please refer to the PIC16F630/676 Programming Specification.

A typical In-Circuit Serial Programming connection is shown in Figure 9-14.

FIGURE 9-14: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



9.11 In-Circuit Debugger

Since in-circuit debugging requires the loss of clock, data and MCLR pins, MPLAB® ICD 2 development with an 14-pin device is not practical. A special 20-pin PIC16F676-ICD device is used with MPLAB ICD 2 to provide separate clock, data and MCLR pins and frees all normally available pins to the user.

This special ICD device is mounted on the top of the header and its signals are routed to the MPLAB ICD 2 connector. On the bottom of the header is an 14-pin socket that plugs into the user's target via the 14-pin stand-off connector.

When the ICD pin on the PIC16F676-ICD device is held low, the In-Circuit Debugger functionality is enabled. This function allows simple debugging functions when used with MPLAB ICD 2. When the microcontroller has this feature enabled, some of the resources are not available for general use. Table 9-10 shows which features are consumed by the background debugger:

TABLE 9-10: DEBUGGER RESOURCES

I/O pins	ICDCLK, ICDDATA
Stack	1 level
Program Memory	Address 0h must be NOP 300h-3FEh

For more information, see 14-Pin MPLAB ICD 2 Header Information Sheet (DS51292) available on Microchip's web site (www.microchip.com).

10.2 Instruction Descriptions

ADDLW Add Literal and W

Syntax: `[label] ADDLW k`

Operands: $0 \leq k \leq 255$

Operation: $(W) + k \rightarrow (W)$

Status Affected: C, DC, Z

Description: The contents of the W register are added to the eight-bit literal 'k' and the result is placed in the W register.

ADDWF Add W and f

Syntax: `[label] ADDWF f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(W) + (f) \rightarrow (\text{destination})$

Status Affected: C, DC, Z

Description: Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

ANDLW AND Literal with W

Syntax: `[label] ANDLW k`

Operands: $0 \leq k \leq 255$

Operation: $(W) .\text{AND.} (k) \rightarrow (W)$

Status Affected: Z

Description: The contents of W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.

ANDWF AND W with f

Syntax: `[label] ANDWF f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(W) .\text{AND.} (f) \rightarrow (\text{destination})$

Status Affected: Z

Description: AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

BCF Bit Clear f

Syntax: `[label] BCF f,b`

Operands: $0 \leq f \leq 127$
 $0 \leq b \leq 7$

Operation: $0 \rightarrow (f)$

Status Affected: None

Description: Bit 'b' in register 'f' is cleared.

BSF Bit Set f

Syntax: `[label] BSF f,b`

Operands: $0 \leq f \leq 127$
 $0 \leq b \leq 7$

Operation: $1 \rightarrow (f)$

Status Affected: None

Description: Bit 'b' in register 'f' is set.

BTFSS Bit Test f, Skip if Set

Syntax: `[label] BTFSS f,b`

Operands: $0 \leq f \leq 127$
 $0 \leq b < 7$

Operation: skip if $(f) = 1$

Status Affected: None

Description: If bit 'b' in register 'f' is '0', the next instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2-cycle instruction.

BTFSC Bit Test, Skip if Clear

Syntax: `[label] BTFSC f,b`

Operands: $0 \leq f \leq 127$
 $0 \leq b \leq 7$

Operation: skip if $(f) = 0$

Status Affected: None

Description: If bit 'b' in register 'f' is '1', the next instruction is executed. If bit 'b', in register 'f', is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2-cycle instruction.

12.2 DC Characteristics: PIC16F630/676-I (Industrial)

		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial					
Param No.	Device Characteristics	Min	Typ†	Max	Units	Conditions	
						VDD	Note
D010	Supply Current (IDD)	—	9	16	μA	2.0	Fosc = 32 kHz LP Oscillator Mode
		—	18	28	μA	3.0	
		—	35	54	μA	5.0	
D011		—	110	150	μA	2.0	Fosc = 1 MHz XT Oscillator Mode
		—	190	280	μA	3.0	
		—	330	450	μA	5.0	
D012		—	220	280	μA	2.0	Fosc = 4 MHz XT Oscillator Mode
		—	370	650	μA	3.0	
		—	0.6	1.4	mA	5.0	
D013		—	70	110	μA	2.0	Fosc = 1 MHz EC Oscillator Mode
		—	140	250	μA	3.0	
		—	260	390	μA	5.0	
D014		—	180	250	μA	2.0	Fosc = 4 MHz EC Oscillator Mode
		—	320	470	μA	3.0	
		—	580	850	μA	5.0	
D015		—	340	450	μA	2.0	Fosc = 4 MHz INTOSC Mode
		—	500	780	μA	3.0	
		—	0.8	1.1	mA	5.0	
D016		—	180	250	μA	2.0	Fosc = 4 MHz EXTRC Mode
		—	320	450	μA	3.0	
		—	580	800	μA	5.0	
D017		—	2.1	2.95	mA	4.5	Fosc = 20 MHz HS Oscillator Mode
		—	2.4	3.0	mA	5.0	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; MCLR = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

12.4 DC Characteristics: PIC16F630/676-E (Extended)

		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
Param No.	Device Characteristics	Min	Typ†	Max	Units	Conditions	
						VDD	Note
D010E	Supply Current (IDD)	—	9	16	μA	2.0	Fosc = 32 kHz LP Oscillator Mode
		—	18	28	μA	3.0	
		—	35	54	μA	5.0	
D011E		—	110	150	μA	2.0	Fosc = 1 MHz XT Oscillator Mode
		—	190	280	μA	3.0	
		—	330	450	μA	5.0	
D012E		—	220	280	μA	2.0	Fosc = 4 MHz XT Oscillator Mode
		—	370	650	μA	3.0	
		—	0.6	1.4	mA	5.0	
D013E		—	70	110	μA	2.0	Fosc = 1 MHz EC Oscillator Mode
		—	140	250	μA	3.0	
		—	260	390	μA	5.0	
D014E		—	180	250	μA	2.0	Fosc = 4 MHz EC Oscillator Mode
		—	320	470	μA	3.0	
		—	580	850	μA	5.0	
D015E		—	340	450	μA	2.0	Fosc = 4 MHz INTOSC Mode
		—	500	780	μA	3.0	
		—	0.8	1.1	mA	5.0	
D016E		—	180	250	μA	2.0	Fosc = 4 MHz EXTRC Mode
		—	320	450	μA	3.0	
		—	580	800	μA	5.0	
D017E		—	2.1	2.95	mA	4.5	Fosc = 20 MHz HS Oscillator Mode
		—	2.4	3.0	mA	5.0	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; MCLR = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

12.6 DC Characteristics: PIC16F630/676-I (Industrial), PIC16F630/676-E (Extended)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D030 D030A D031 D032 D033 D033A	V _{IL}	Input Low Voltage I/O ports with TTL buffer with Schmitt Trigger buffer MCLR, OSC1 (RC mode) OSC1 (XT and LP modes) OSC1 (HS mode)	V _{SS} V _{SS} V _{SS} V _{SS} V _{SS} V _{SS}	— — — — — —	0.8 0.15 V _{DD} 0.2 V _{DD} 0.2 V _{DD} 0.3 0.3 V _{DD}	V V V V V V	4.5V ≤ V _{DD} ≤ 5.5V Otherwise Entire range (Note 1) (Note 1)
D040 D040A D041 D042 D043 D043A D043B	V _{IH}	Input High Voltage I/O ports with TTL buffer with Schmitt Trigger buffer MCLR OSC1 (XT and LP modes) OSC1 (HS mode) OSC1 (RC mode)	2.0 (0.25 V _{DD} +0.8) 0.8 V _{DD} 0.8 V _{DD} 1.6 0.7 V _{DD} 0.9 V _{DD}	— — — — — — —	V _{DD} V _{DD} V _{DD} V _{DD} V _{DD} V _{DD} V _{DD}	V V V V V V V	4.5V ≤ V _{DD} ≤ 5.5V otherwise entire range (Note 1) (Note 1)
D070	I _{PUR}	PORTA Weak Pull-up Current	50*	250	400*	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
D060 D060A D060B D061 D063	I _{IL}	Input Leakage Current⁽³⁾ I/O ports Analog inputs V _{REF} MCLR ⁽²⁾ OSC1	— — — — —	± 0.1 ± 0.1 ± 0.1 ± 0.1 ± 0.1	± 1 ± 1 ± 1 ± 5 ± 5	μA μA μA μA μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , Pin at high-impedance V _{SS} ≤ V _{PIN} ≤ V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP osc configuration
D080 D083	V _{OL}	Output Low Voltage I/O ports OSC2/CLKOUT (RC mode)	— —	— —	0.6 0.6	V V	I _{OL} = 8.5 mA, V _{DD} = 4.5V (Ind.) I _{OL} = 1.6 mA, V _{DD} = 4.5V (Ind.) I _{OL} = 1.2 mA, V _{DD} = 4.5V (Ext.)
D090 D092	V _{OH}	Output High Voltage I/O ports OSC2/CLKOUT (RC mode)	V _{DD} - 0.7 V _{DD} - 0.7	— —	— —	V V	I _{OH} = -3.0 mA, V _{DD} = 4.5V (Ind.) I _{OH} = -1.3 mA, V _{DD} = 4.5V (Ind.) I _{OH} = -1.0 mA, V _{DD} = 4.5V (Ext.)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

12.8 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created with one of the following formats:

- 1. TppS2ppS
- 2. TppS

T			
F	Frequency	T	Time

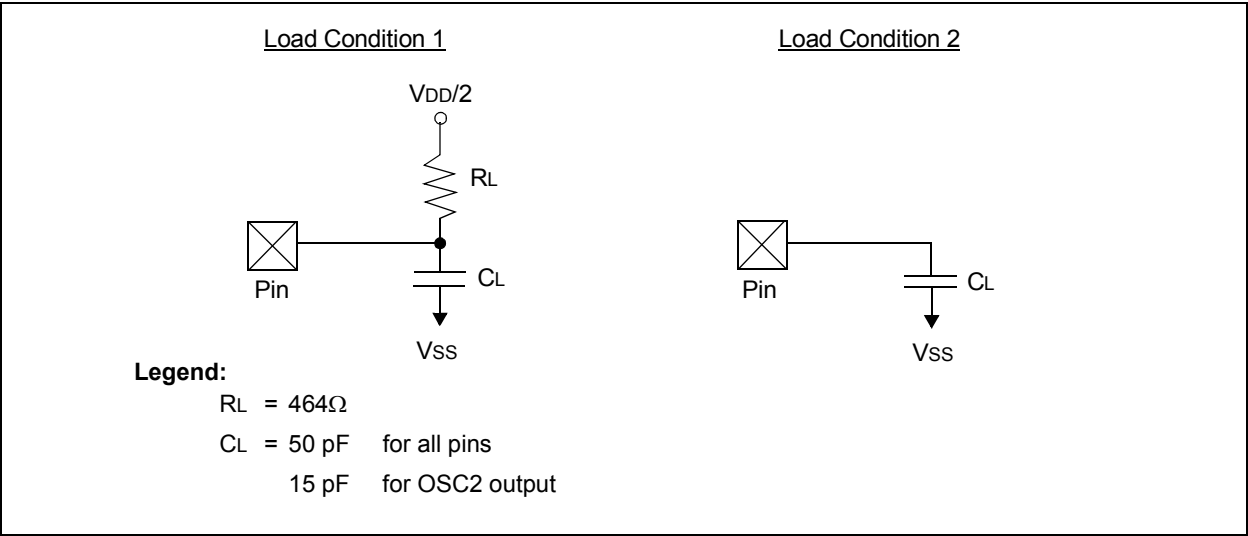
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	\overline{RD}
cs	\overline{CS}	rw	\overline{RD} or \overline{WR}
di	SDI	sc	SCK
do	SDO	ss	\overline{SS}
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	\overline{MCLR}	wr	\overline{WR}

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 12-4: LOAD CONDITIONS



PIC16F630/676

FIGURE 13-3: TYPICAL IPD vs. VDD OVER TEMP (+125°C)

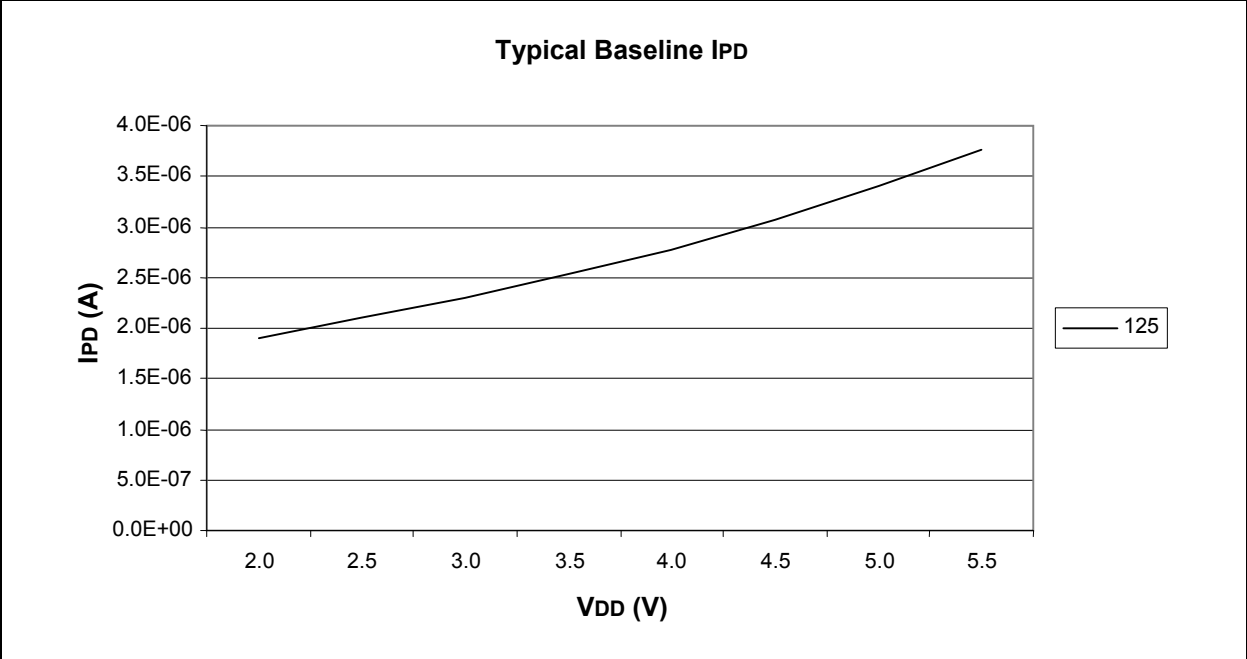
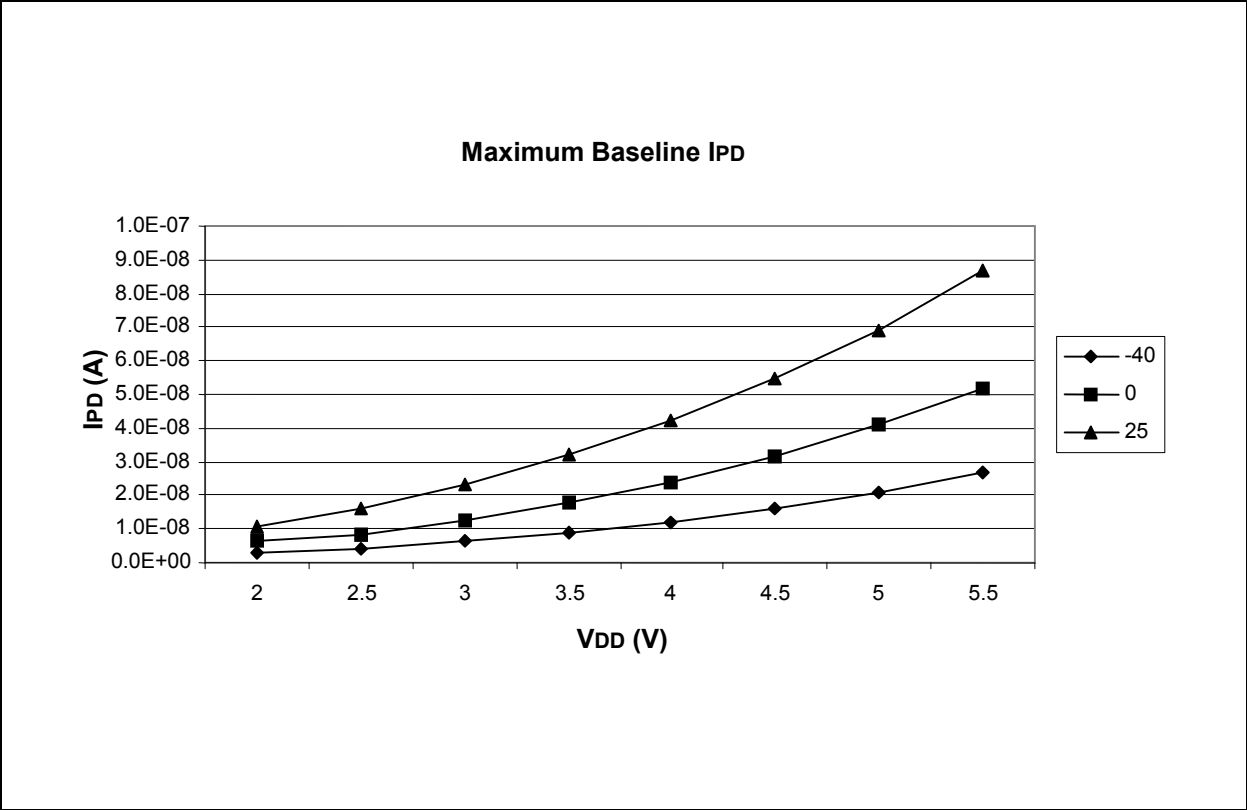


FIGURE 13-4: MAXIMUM IPD vs. VDD OVER TEMP (-40°C TO +25°C)



PIC16F630/676

APPENDIX C: DEVICE MIGRATIONS

This section is intended to describe the functional and electrical specification differences when migrating between functionally similar devices (such as from a PIC16C74A to a PIC16C74B).

Not Applicable

APPENDIX D: MIGRATING FROM OTHER PIC[®] DEVICES

This discusses some of the issues in migrating from other PIC devices to the PIC16F6XX family of devices.

D.1 PIC12C67X to PIC12F6XX

TABLE 1: FEATURE COMPARISON

Feature	PIC12C67X	PIC16F6XX
Max Operating Speed	10 MHz	20 MHz
Max Program Memory	2048 bytes	1024 bytes
A/D Resolution	8-bit	10-bit
Data EEPROM	16 bytes	64 bytes
Oscillator Modes	5	8
Brown-out Detect	N	Y
Internal Pull-ups	RA0/1/3	RA0/1/2/4/5
Interrupt-on-change	RA0/1/3	RA0/1/2/3/4/5
Comparator	N	Y

Note: This device has been designed to perform to the parameters of its data sheet. It has been tested to an electrical specification designed to determine its conformance with these parameters. Due to process differences in the manufacture of this device, this device may have different performance characteristics than its earlier version. These differences may cause this device to perform differently in your application than the earlier version of this device.